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CORE



COVER SHEET

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PATENT AND TRADEMARK OFFICE

TO THE HONORABLE DIRECTOR OF PATENT AND TRADEMARK OFFICE. PLEASE RECORD THE ATTACHED ORIGINAL DOCUMENTS OR COPY THEREOF. 101827180

1. Name of conveying party(ies):  
(a) JIN, Ho Tae  
(b) KIM, Heui-Seong  
(c) KIM, Sang-Young  
Additional name(s) of conveying party(ies) attached?  
 Yes  No

8-9-01

2. Name and address of receiving party(ies):  
Name: Samsung Electronics Co., Ltd.  
Street Address: 416, Maetan-dong, Paldal-gu  
City: Suwon, Kyonggi-do  
Country: Korea

3. Nature of Conveyance:  
 Assignment  Merger  
 Security Agreement  Change of Name  
 Other \_\_\_\_\_  
Execution Date: October 27, 2000

Name and address of receiving party(ies):  
Name:  
Street Address:  
City:  
Country:  
Additional name(s) & address(es) attached?  
 Yes  No

4. Application number(s) or patent number(s): **09/632,079 filed August 2, 2000**  
If this document is being filed together with a new application, the execution date of the application is: \_\_\_\_\_

A. Patent Application No.(s) - 09/632,079  
Title: **Semiconductor Chip Packaging System And A Semiconductor Chip Packaging Method Using The Same**

B. Patent No.(s)

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:  
Name: David W. Heid  
Internal Address: SKJERVEN MORRILL MacPHERSON LLP  
Street Address: 25 METRO DRIVE, SUITE 700  
City SAN JOSE State CA Zip 95110

6. Total number of applications and patents involved: \_\_\_\_\_

7. Total fee (37 CFR 3.41): \$40.00  
 Authorized to be charged to Deposit Account 19-2386  
 Charge Deposit Account 19-2386 for any additional fees required for this conveyance and credit deposit account 19-2386 any amounts overpaid

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8. Statement and signature.  
*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*  
David W. Heid  
Name of Person Signing Signature Date 8/09/01

Total number of pages comprising cover sheet: 1

## ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, we Ho-Tae JIN, Heui-Seong KIM, and Sang-Young KIM hereby sell, assign and transfer to Samsung Electronics Co., Ltd., a Korean corporation, having a place of business at 416, Maetan-dong, Paldal-gu, Suwon, Kyonggi-do, Korea, its successors and assigns, the entire right, title and interest throughout the world in: our invention,

### Semiconductor Chip Packaging System And A Semiconductor Chip Packaging Method Using The Same

described in a United States patent application No. 09/632,079; all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof; and all rights of priority resulting from the filing of said applications. We authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from us. We agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, their successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request the Commissioner of Patents and Trademarks to issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 27 day of October, 2000.

Ho Tae Jin

Ho-Tae JIN

Executed this 27 day of October, 2000.

Heui - Seong Kim

Heui-Seong KIM

Executed this 27 day of October, 2000.

Sang - Young Kim

Sang-Young KIM